

ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1 ICP Web Site for information on IPC-1752 Standard http://www.ipc.org/IPC-175x

Form Type*
Distribute

Declaration Class* Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information								
Company Name *	Company Unique ID	- 1	Response Date*					
Fairchild Semiconductor	00-489-5751	Dun & Bradstreet	Sat, Aug 09, 2014 02:32 AM					
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Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *					
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com					

Requester Item Number	Mfr Ite	em Number Mfr Item Name		Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type		
FDG6303N	FDC	66303N	SC70-6 (EutDA	_G)	internal cebu		TERNAL CEBU	0.005759	g	Each		
Manufacturing Process Information												
Terminal Finish	Base Alloy	J-STD-02	-STD-020 MSL Rating		Peak Process Body Temperature		Max Time at Peak Temperature		No Ret	No Reflow cycles		
Matte Tin (Sn)	Alloy 42		1	260 C		С	30 sec		30 seconds		3	

^{*} Required Field

RoHS Material Composition Declaration

Declaration Type * Custom

RoHS Directive 2011/65/EU **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration *

1 - Item(s) does not contain RoHS restricted substances per the definition above

Supplier Acceptance * Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU

Declaration Signature

Supplier Signature

DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

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Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name SC70-6 (EutDA_G)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	0.148	Supplier		Silicon	0.148	7440-21-3	25701
Encapsulation	Thermoplastics	3.224	Supplier		Carbon Black	0.032	1333-86-4	5599
			Supplier		Epoxy Resin	0.645	29690-82-2	111983
			Supplier		Silica, vitreous	2.547	60676-86-0	442332
Lead Frame	Other Ferrous alloys, non-stainless steels	2.086	Supplier		Cobalt	0.010	7440-48-4	1823
			Supplier		Iron	1.160	7439-89-6	201439
			Supplier		Manganese	0.017	7439-96-5	2900
			В	Nickel (external applications only)	Nickel	0.878	7440-02-0	152468
			Supplier		Silicon	0.006	7440-21-3	1089
			Supplier		Silver	0.015	7440-22-4	2605
Plating	Other Nonferrous metals & alloys	0.274	Supplier		Tin	0.274	7440-31-5	47581
Wire Bond	Precious metals	0.026	Supplier		Gold	0.026	7440-57-5	4480